



#10/c  
GA  
12/12/02  
Attorney's Docket No.: 082225.P1423D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application for:

**Chung Lam**

Serial No.: 09/336,116

Filed: June 18, 1999

For: **BOARD LEVEL DECAPSULATOR**

Examiner: Ahmed, S.

Art Group: 1746

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed September 3, 2002, Applicant respectfully requests consideration in view of the following amendments and remarks:

**IN THE CLAIMS**

*(50, 01)* 9. (Twice Amended) A method for decapsulating installed integrated circuit (IC) packages, comprising:  
receiving an IC package, permanently installed onto a printed circuit board;  
placing the installed IC package onto a tray;  
clamping an injection head onto the installed IC package; and,  
spraying decapsulation fluid onto the installed IC package through the injection head.

*(C1)* 10. (Twice Amended) The method as recited in claim 9, further comprising:  
moving a stub that is plugged into the tray and which supports the printed circuit board of the installed IC package before the installed IC package is placed onto said tray.

*(C2)* 11. (Amended) The method as recited in claim 9, further comprising:  
controlling a flow of the decapsulation fluid through a pair of tubes that couple an extender to the injection head using a corresponding pair of valves.